

ABSTRACT

Method and device for drying circuit substrates (13), in particular semiconductor substrates, in which a circuit surface (30) of the circuit
5 substrate is flushed using a flushing liquid (10) in a flushing step and the circuit surface is dried in a subsequent drying step, the circuit substrate being moved in the flushing step in the direction of its planar extension transversely and in relation to a liquid level (28) of the flushing liquid in such a way that a liquid meniscus forms at a transition area between the
10 circuit surface and the liquid level, which changes because of the relative movement, and thermal radiation (36) is applied to the transition area wetted by the liquid meniscus in the drying step.

(Fig. 1)